

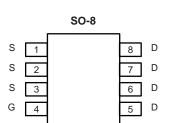
N-Channel 150 V (D-S) MOSFET

PRODUCT SUMMARY						
V _{DS} (V)	$R_{DS(on)}(\Omega)$	I _D (A) ^a	Q _g (Typ.)			
150	0.080 at V _{GS} = 10 V	5.4	23 nC			
150	0.085 at V _{GS} = 8 V	4.5	23110			

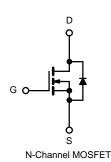
FEATURES

- Halogen-free According to IEC 61249-2-21 Definition
- Extremely Low Q_{gd} for Switching Losses
- 100 % R_g Tested
- 100 % Avalanche Tested
- Compliant to RoHS Directive 2002/95/EC





Top View



APPLICATIONS

· Primary Side Switch

Parameter	Symbol	Limit	Unit		
Drain-Source Voltage		V _{DS}	150	V	
Gate-Source Voltage		V_{GS}	± 20		
-	T _C = 25 °C		5.4		
Continuous Drain Current (T. 150 °C)	T _C = 70 °C	1 . [5.1		
Continuous Drain Current (T _J = 150 °C)	T _A = 25 °C	l _D	5.0 ^{b, c}		
	T _A = 70 °C		4.5 ^{b, c}	Α	
Pulsed Drain Current		I _{DM}	22	A	
Continuous Source-Drain Diode Current	T _C = 25 °C		4.5		
Continuous Source-Drain Diode Current	T _A = 25 °C	Is	2.6 ^{b, c}		
Single Pulse Avalanche Current	L = 0.1 mH	I _{AS}	20		
Single Pulse Avalanche Energy	L = 0.111111	E _{AS}	20	mJ	
	T _C = 25 °C		5.9		
Maximum Power Dissipation	T _C = 70 °C]	3.8	w	
Maximum Power Dissipation	T _A = 25 °C	P _D	3.1 ^{b, c}	VV	
	T _A = 70 °C	1 1	2 ^{b, c}		
Operating Junction and Storage Temperature Range		T _J , T _{stq}	- 55 to 150	°C	

THERMAL RESISTANCE RATINGS							
Parameter		Symbol	Typical	Maximum	Unit		
Maximum Junction-to-Ambient ^{b, †}	t ≤ 10 s	R _{thJA}	33	40	°C/W		
Maximum Junction-to-Foot (Drain)	Steady State	$R_{th,IF}$	17	21	C/VV		

Notes

- a. Based on T_C = 25 °C.
- b. Surface mounted on 1" x 1" FR4 board.
- c. t = 10 s.
- d. Maximum under steady state conditions is 80 °C/W.



Parameter	Symbol	Test Conditions	Min.	Тур.	Max.	Unit
Static			•			
Drain-Source Breakdown Voltage	V _{DS}	$V_{GS} = 0 \text{ V, } I_D = 250 \mu\text{A}$	150			V
V _{DS} Temperature Coefficient	$\Delta V_{DS}/T_{J}$			172		\//90
V _{GS(th)} Temperature Coefficient	$\Delta V_{GS(th)}/T_{J}$	$I_D = 250 \mu A$		- 10		mV/°C
Gate-Source Threshold Voltage	V _{GS(th)}	$V_{DS} = V_{GS}$, $I_{D} = 250 \mu\text{A}$	1.2		2.5	V
Gate-Source Leakage	I _{GSS}	$V_{DS} = 0 \text{ V}, V_{GS} = \pm 20 \text{ V}$			± 100	nA
Zana Oata Valtana Busin Oamani	I _{DSS}	V _{DS} = 100 V, V _{GS} = 0 V			1	
Zero Gate Voltage Drain Current		V _{DS} = 100 V, V _{GS} = 0 V, T _J = 55 °C			10	μΑ
On-State Drain Current ^a	I _{D(on)}	$V_{DS} \ge 10 \text{ V}, V_{GS} = 10 \text{ V}$	30			Α
Davis Course On Otata Basistana 3	` '	V _{GS} = 10 V, I _D = 5 A	0.080			
Drain-Source On-State Resistance ^a	R _{DS(on)}	$V_{GS} = 8 \text{ V, } I_{D} = 5 \text{ A}$		0.085	Ω	
Forward Transconductance ^a	9 _{fs}	V _{DS} = 15 V, I _D = 5 A		23		S
Dynamic ^b						
Input Capacitance	C _{iss}			1735		
Output Capacitance	C _{oss}	$V_{DS} = 50 \text{ V}, V_{GS} = 0 \text{ V}, f = 1 \text{ MHz}$		160		pF
Reverse Transfer Capacitance	C _{rss}			37		
Total Gate Charge	Q _g	V _{DS} = 75 V, V _{GS} = 10 V, I _D = 5 A	28.5	43		
				23	35	
Gate-Source Charge	Q_{gs}	$V_{DS} = 75 \text{ V}, V_{GS} = 8 \text{ V}, I_{D} = 5 \text{ A}$		8		nC
Gate-Drain Charge	Q _{gd}			6.5		
Gate Resistance	R _g	f = 1 MHz		0.85	1.3	Ω
Turn-on Delay Time	t _{d(on)}			14	21	
Rise Time	t _r	V_{DD} = 50 V, R_L = 10 Ω		12	18	
Turn-Off Delay Time	t _{d(off)}	$I_D \cong 5 \text{ A}, V_{GEN} = 10 \text{ V}, R_g = 1 \Omega$		22	33	
Fall Time	t _f			6	10	200
Turn-On Delay Time	t _{d(on)}			16	24	ns
Rise Time	t _r	V_{DD} = 50 V, R_L = 10 Ω		12	18	
Turn-Off Delay Time	t _{d(off)}	$I_D \cong 5 \text{ A}, V_{GEN} = 8 \text{ V}, R_g = 1 \Omega$		20	30	
Fall Time	t _f			7	12	
Drain-Source Body Diode Characteristi	cs					
Continuous Source-Drain Diode Current	I _S	T _C = 25 °C			7.7	Α
Pulse Diode Forward Current ^a	I _{SM}				50	_ ^
Body Diode Voltage	V _{SD}	I _S = 2.6 A		0.77	1.2	V
Body Diode Reverse Recovery Time	t _{rr}			63	95	ns
Body Diode Reverse Recovery Charge	Q _{rr}	L = 5 A dl/dt = 100 A/us T = 25 °C		110	165	nC
Reverse Recovery Fall Time	t _a	$I_F = 5 \text{ A}, \text{ dI/dt} = 100 \text{ A/}\mu\text{s}, T_J = 25 \text{ °C}$		49		20
Reverse Recovery Rise Time	t _b	7		14		ns

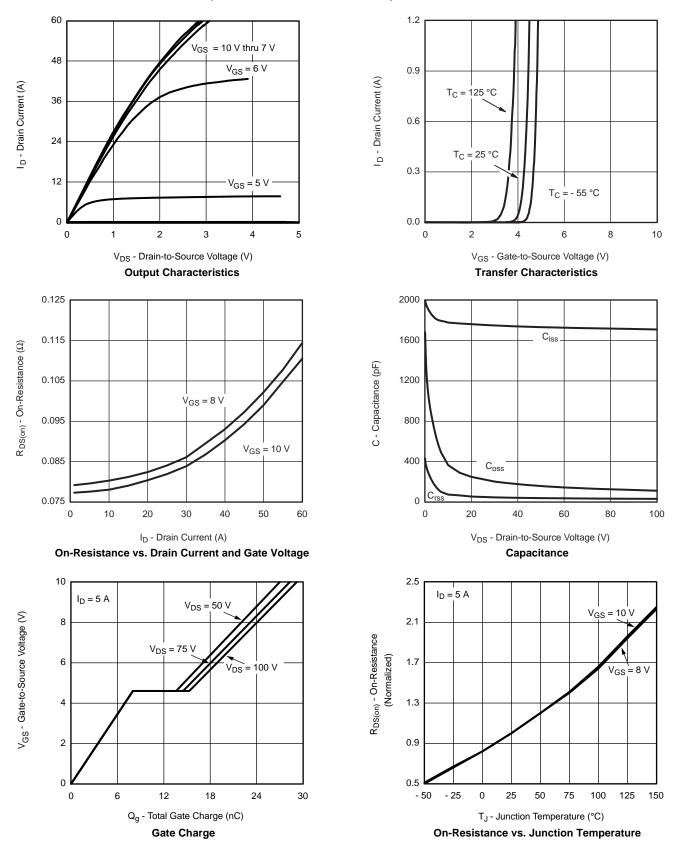
Notes:

Stresses beyond those listed under "Absolute Maximum Ratings" may cause permanent damage to the device. These are stress ratings only, and functional operation of the device at these or any other conditions beyond those indicated in the operational sections of the specifications is not implied. Exposure to absolute maximum rating conditions for extended periods may affect device reliability.

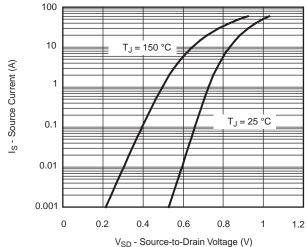
a. Pulse test; pulse width $\leq 300~\mu s,$ duty cycle $\leq 2~\%$

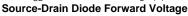
a. Guaranteed by design, not subject to production testing.

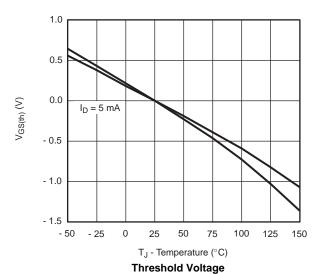




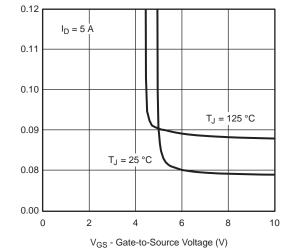




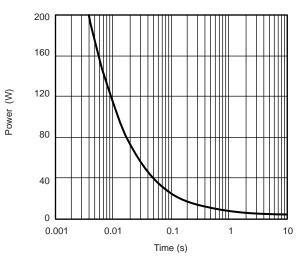




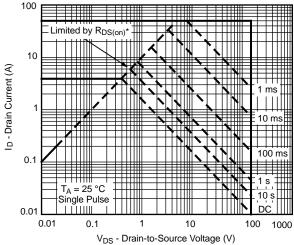
R_{DS(on)} - Drain-to-Source On-Resistance (Ω)



On-Resistance vs. Gate-to-Source Voltage



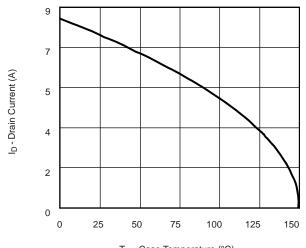
Single Pulse Power, Junction-to-Ambient



* V_{GS} > minimum V_{GS} at which R_{DS(on)} is specified

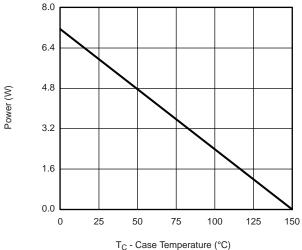
Safe Operating Area, Junction-to-Ambient

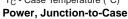


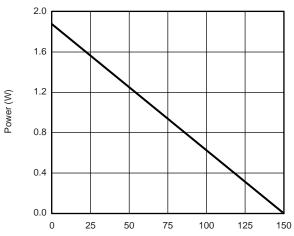


T_C - Case Temperature (°C)





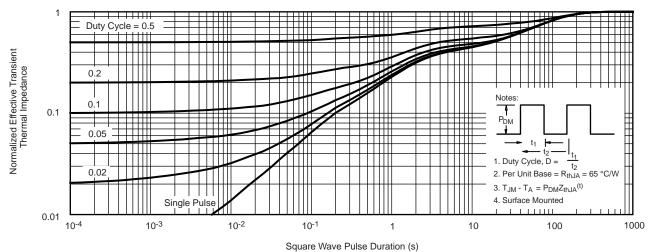




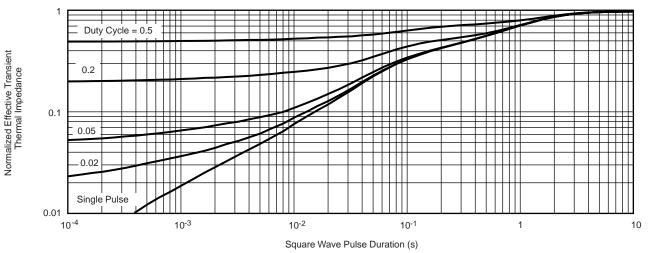
T_A - Ambient Temperature (°C) **Power, Junction-to-Ambient**

^{*} The power dissipation P_D is based on $T_{J(max)} = 150$ °C, using junction-to-case thermal resistance, and is more useful in settling the upper dissipation limit for cases where additional heatsinking is used. It is used to determine the current rating, when this rating falls below the package limit.





Normalized Thermal Transient Impedance, Junction-to-Ambient

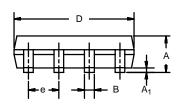


Normalized Thermal Transient Impedance, Junction-to-Foot



SOIC (NARROW): 8-LEAD JEDEC Part Number: MS-012





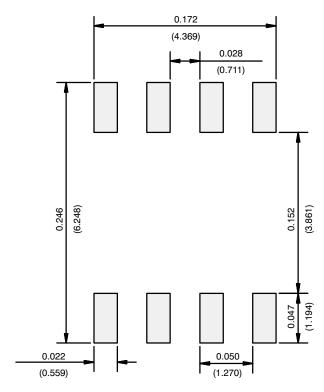


	MILLIMETERS		INC	INCHES		
DIM	Min	Max	Min	Max		
Α	1.35	1.75	0.053	0.069		
A ₁	0.10	0.20	0.004	0.008		
В	0.35	0.51	0.014	0.020		
С	0.19	0.25	0.0075	0.010		
D	4.80	5.00	0.189	0.196		
E	3.80	4.00	0.150	0.157		
е	1.27 BSC		0.050 BSC			
Н	5.80	6.20	0.228	0.244		
h	0.25	0.50	0.010	0.020		
L	0.50	0.93	0.020	0.037		
q	0°	8°	0°	8°		
S	0.44	0.64	0.018	0.026		
FCN: C-06527-Rev I 11-Sen-06						

ECN: C-06527-Rev. I, 11-Sep-06 DWG: 5498



RECOMMENDED MINIMUM PADS FOR SO-8



Recommended Minimum Pads Dimensions in Inches/(mm)



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